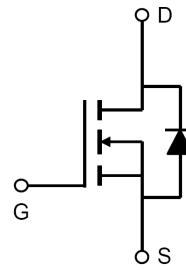
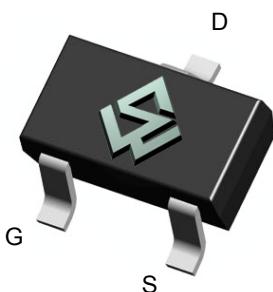


60V Single N-Channel Enhancement-Mode MOSFET

| General Description | Product Summary | |
|---------------------------|---|-----------------------|
| • Low gate charge. | $\bullet \text{BV}_{\text{DSS}}$ | 60V |
| • Use as a load switch. | $\bullet R_{\text{DS(on)}} @ V_{\text{GS}} = 10\text{V}$ | $< 90\text{m}\Omega$ |
| • Use in PWM applications | $\bullet R_{\text{DS(on)}} @ V_{\text{GS}} = 4.5\text{V}$ | $< 100\text{m}\Omega$ |

SOT-23



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Maximum | Units |
|---|-----------------------|------------|-------|
| Drain-Source Voltage | V_{DS} | 60 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current ($T_A=25^\circ\text{C}$) | I_D | 2.3 | A |
| Drain Current ($T_A=75^\circ\text{C}$) | | 1.8 | A |
| Pulsed Drain Current ^a | I_{DM} | 9.0 | A |
| Power Dissipation ^b ($T_A=25^\circ\text{C}$) | P_D | 1.0 | W |
| Power Dissipation ^b ($T_A=75^\circ\text{C}$) | | 0.6 | W |
| Junction and Storage Temperature Range | T_J, T_{STG} | -55 ~ +150 | °C |

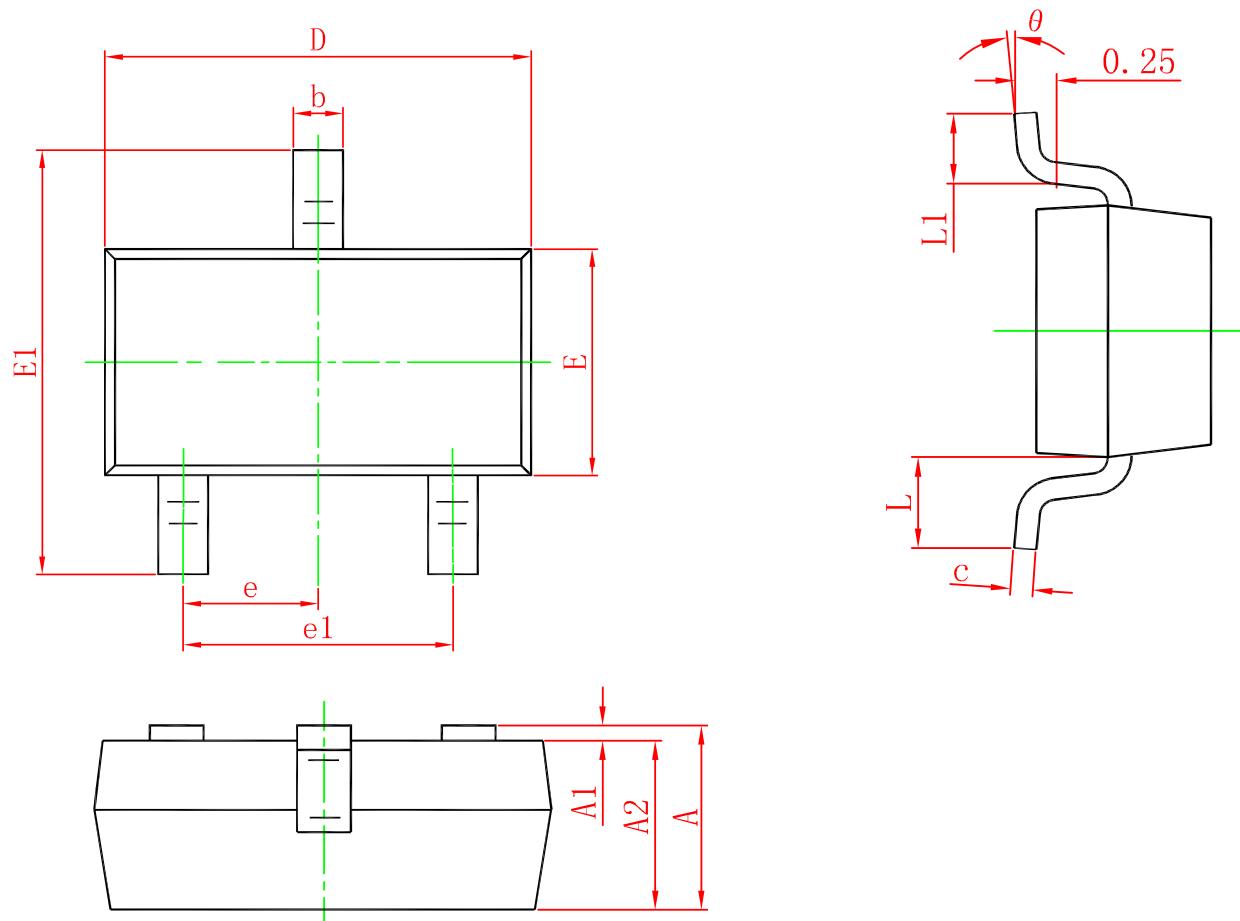
Thermal Characteristics

| Parameter | Symbol | Maximum | Units |
|--|-----------------|---------|-------|
| Junction-to-Ambient ^a ($t \leq 10\text{s}$) | $R_{\theta JA}$ | 100 | °C/W |
| Junction-to-Ambient ^{a,d} (Steady-State) | | 130 | °C/W |
| Junction-to-Lead (Steady-State) | $R_{\theta JL}$ | 90 | °C/W |

| Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted) | | | | | | |
|--|---------------------------------------|--|------------|------------|------------|------------------|
| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
| Off Characteristics | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{\text{GS}} = 0\text{V}$, $I_D = 250\mu\text{A}$ | 60 | | | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{\text{DS}} = 60\text{V}$, $V_{\text{GS}} = 0\text{V}$ | | | 1 | μA |
| I_{GSS} | Gate-Body Leakage Current | $V_{\text{GS}} = \pm 20\text{V}$, $V_{\text{DS}} = 0\text{V}$ | | | ± 100 | nA |
| On Characteristics | | | | | | |
| $V_{\text{GS(th)}}$ | Gate Threshold Voltage | $V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250\mu\text{A}$ | 1.0 | | 2.5 | V |
| $R_{\text{DS(ON)}}$ | Drain-Source On-State Resistance | $V_{\text{GS}} = 10\text{V}$, $I_D = 2.0\text{A}$ | | 78 | 90 | $\text{m}\Omega$ |
| | | $V_{\text{GS}} = 4.5\text{V}$, $I_D = 1.5\text{A}$ | | 89 | 100 | $\text{m}\Omega$ |
| g_{FS} | Forward Transconductance | $V_{\text{DS}} = 5.0\text{V}$, $I_D = 1.0\text{A}$ | | 13 | | S |
| Drain-Source Diode Characteristics | | | | | | |
| V_{SD} | Diode Forward Voltage | $V_{\text{GS}} = 0\text{V}$, $I_S = 1.0\text{A}$ | | | 1.2 | V |
| I_S | Maximum Body-Diode Continuous Current | | | | 2.3 | A |
| Dynamic Characteristics | | | | | | |
| C_{iss} | Input Capacitance | $V_{\text{DS}} = 15\text{V}$, $V_{\text{GS}} = 0\text{V}$ $f = 1.0\text{MHz}$ | | 514 | | pF |
| C_{oss} | Output Capacitance | | | 39 | | pF |
| C_{rss} | Reverse Transfer Capacitance | | | 27 | | pF |
| Q_g | Total Gate Charge | $V_{\text{DS}} = 48\text{V}$, $I_D = 2.0\text{A}$ $V_{\text{GS}} = 4.5\text{V}$ | | 7 | | nC |
| Q_{gs} | Gate-Source Charge | | | 1.72 | | nC |
| Q_{gd} | Gate-Drain Charge | | | 2.2 | | nC |
| $t_{\text{D(ON)}}$ | Turn-On Delay Time | $V_{\text{DD}} = 30\text{V}$, $I_D = 2.0\text{A}$ $V_{\text{GS}} = 10\text{V}$ $R_{\text{GEN}} = 3.3 \text{ ohm}$ | | 1.8 | | ns |
| t_r | Turn-On Rise Time | | | 7.3 | | ns |
| $t_{\text{D(OFF)}}$ | Turn-Off Delay Time | | | 24.5 | | ns |
| t_f | Turn-Off Fall Time | | | 16 | | ns |

- a. Repetitive rating, Pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$
- b. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using $\leq 10\text{s}$ junction-to-ambient thermal resistance.
- c. The value of $R_{\theta_{JA}}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application depends on the user's specific board design.
- d. The $R_{\theta_{JA}}$ is the sum of the thermal impedance from junction to lead $R_{\theta_{JL}}$ and lead to ambient.

SOT-23 Package Outline



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|-----------|---------------------------|------------|----------------------|-------|
| | Min. | Max | Min. | Max. |
| A | 0.900 | 1.150 | 0.035 | 0.045 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| A2 | 0.900 | 1.050 | 0.035 | 0.041 |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| c | 0.080 | 0.150 | 0.003 | 0.006 |
| D | 2.800 | 3.000 | 0.110 | 0.118 |
| E | 1.200 | 1.400 | 0.047 | 0.055 |
| E1 | 2.250 | 2.550 | 0.089 | 0.100 |
| e | 0.950 TYP. | | 0.037 TYP. | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 |
| L | 0.550 REF. | 0.022 REF. | | |
| θ | 0.300 | 0.500 | 0.012 | 0.020 |

单击下面可查看定价，库存，交付和生命周期等信息

>>[SiliconWisdom\(矽睿半导体\)](#)